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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Sheet 1 of 4

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| Substitute for form 1449A/PTO | | <i>Complete if Known</i> | |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT | | Application Number | 09/874,631 |
| <i>(use as many sheets as necessary)</i> | | Filing Date | June 5, 2001 |
| | | First Named Inventor | Moon et al. |
| | | Group Art Unit | 2815 |
| | | Examiner Name | S. Clark |
| Sheet | 1 | of | 4 |
| | | Attorney Docket Number | 2269-4368US (99-0959.00/US) |

U.S. PATENT DOCUMENTS

| Examiner Initials * | Cite No. ¹ | Document Number | Publication Date MM-DD-YYYY | Name of Patentee or Applicant of Cited Document | Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear |
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| Examiner Name | S. Clark |
| Attorney Docket Number | 2269-4168IUS (99-0959.00/IUS) |

OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS

| Examiner Initials * | Cite No. ¹ | Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published. | T ² |
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| Examiner Signature |  | Date Considered | 11/27/01 |
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|---------------------|-----------------------|---|----------------|
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